

***Amendments to the Claims***

This listing of claims will replace all prior versions, and listings, of claims in the application.

1-11. *(Canceled)*

12. *(Currently Amended)* A wafer alignment system ~~configured to reduce wafer slipping~~, comprising:

a wafer chuck configured to receive a wafer; and

an expandable annular tube coupled to the wafer chuck and configured to expand the wafer chuck without substantially expanding the wafer to reduce wafer slipping, such that an initial stress at an interface between the wafer and the wafer chuck is created, wherein said annular tube having an outer surface which is coupled to an outer edge of the wafer chuck such that the outer surface of said annular tube is substantially outside of the wafer chuck to uniformly expand the wafer chuck ~~wherein the expandable annular tube is sealed to be pressurized and configured to expand to in turn expand the wafer chuck when pressurized.~~

13. *(Canceled)*

14. *(Canceled)*

15. *(Canceled)*

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16. - 22.        *(Canceled)*

23.        *(Canceled)*

24.        *(Previously Presented)* The system of claim 12, wherein said annular tube comprises a metal.

25.        *(Previously Presented)* The system of claim 12, wherein said annular tube comprises a plastic.

26.        *(Previously Presented)* The system of claim 12, wherein said annular tube includes a cavity, and wherein the cavity is configured to be filled with one of a gas and a liquid.

27.        *(Previously Presented)* The system of claim 12, further comprising:  
a temperature sensor coupled to the wafer chuck.

28.        *(Previously Presented)* The system of claim 12, wherein said wafer chuck is configured to releasably secure or hold the wafer by vacuum clamping.

29.        *(Previously Presented)* The system of claim 12, wherein said wafer chuck is configured to releasably secure or hold the wafer by electrostatic clamping.

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30. (New) The system of claim 12, wherein said annular tube is sealed to be pressurized and configured to expand to in turn expand the wafer chuck when pressurized.
31. (New) A wafer alignment system, comprising:  
a wafer stage;  
a wafer chuck configured to receive a wafer; and  
an expandable annular tube coupled to the wafer chuck and configured to uniformly expand the wafer chuck prior to exposure without substantially expanding the wafer to provide an overlay correction by reducing wafer slipping during the exposure after the wafer has been aligned to the wafer stage, such that an initial stress at an interface between the wafer and the wafer chuck is created, wherein said annular tube is a sealed tube that includes a cavity which is disposed along the circumference of the wafer chuck.
32. (New) The wafer alignment system of claim 31, wherein said annular tube comprises a metal.
33. (New) The wafer alignment system of claim 31, wherein said annular tube comprises a plastic.

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34.    (New)   The wafer alignment system of claim 31, wherein said cavity is configured to be filled with one of a gas and a liquid.
35.    (New)   The wafer alignment system of claim 31, further comprising:  
a temperature sensor coupled to the wafer chuck.
36.    (New)   The wafer alignment system of claim 31, wherein the wafer chuck is configured to releasably secure or hold the wafer by vacuum clamping.
37.    (New)   The wafer alignment system of claim 31, wherein the wafer chuck is configured to releasably secure or hold the wafer by electrostatic clamping.
38.    (New)   The wafer alignment system of claim 31, wherein said sealed tube is sealed to be pressurized and configured to expand to in turn expand the wafer chuck when pressurized.